

IN THE CLAIMS

Cancel claims 1-34 and 36-43.

1 - 34 (Canceled)

35. (Original) A method of connecting a semiconductor or microelectronic device having one or more electrical contacts to a substrate having one or more receiving contacts, comprising the steps of:

disposing between the device and the substrate a reactive multilayer foil composed of one or more first regions that can react exothermically to form electrically conductive regions and one or more second regions which are non-conductive or react to form non-conductive material.;

registering the contacts of the device, the contacts of the substrate and the first regions of the foil,

pressing the device and the substrate together against the foil; and

igniting the foil.

Attorney Docket No.: 13631-48

36 - 43 (Canceled)